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Notice of Allowability	Application No.	Applicant(s)	
	10/605,167	CHIDAMBARRAO ET AL.	
	Examiner	Art Unit	
	Pamela E Perkins	2822	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address--

All claims being allowable, PROSECUTION ON THE MERITS IS (OR REMAINS) CLOSED in this application. If not included herewith (or previously mailed), a Notice of Allowance (PTOL-85) or other appropriate communication will be mailed in due course. **THIS NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATENT RIGHTS.** This application is subject to withdrawal from issue at the initiative of the Office or upon petition by the applicant. See 37 CFR 1.313 and MPEP 1308.

1. ☒ This communication is responsive to *the after final amendment filed on 2 December 2004*.

2. ☒ The allowed claim(s) is/are *7-18*.

3. ☒ The drawings filed on *12 September 2003* are accepted by the Examiner.

4. ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
   a) ☐ All b) ☐ Some* c) ☐ None of the:
      1. ☐ Certified copies of the priority documents have been received.
      2. ☐ Certified copies of the priority documents have been received in Application No. _____ .
      3. ☐ Copies of the certified copies of the priority documents have been received in this national stage application from the International Bureau (PCT Rule 17.2(a)).

   * Certified copies not received: _____.

Applicant has THREE MONTHS FROM THE "MAILING DATE" of this communication to file a reply complying with the requirements noted below. Failure to timely comply will result in ABANDONMENT of this application.
THIS THREE-MONTH PERIOD IS NOT EXTENDABLE.

5. ☐ A SUBSTITUTE OATH OR DECLARATION must be submitted. Note the attached EXAMINER'S AMENDMENT or NOTICE OF INFORMAL PATENT APPLICATION (PTO-152) which gives reason(s) why the oath or declaration is deficient.

6. ☐ CORRECTED DRAWINGS (as "replacement sheets") must be submitted.
   (a) ☐ including changes required by the Notice of Draftsperson's Patent Drawing Review (PTO-948) attached
      1) ☐ hereto or 2) ☐ to Paper No./Mail Date _____.
   (b) ☐ including changes required by the attached Examiner's Amendment / Comment or in the Office action of Paper No./Mail Date _____.

Identifying indicia such as the application number (see 37 CFR 1.84(c)) should be written on the drawings in the front (not the back) of each sheet. Replacement sheet(s) should be labeled as such in the header according to 37 CFR 1.121(d).

7. ☐ DEPOSIT OF and/or INFORMATION about the deposit of BIOLOGICAL MATERIAL must be submitted. Note the attached Examiner's comment regarding REQUIREMENT FOR THE DEPOSIT OF BIOLOGICAL MATERIAL.

Attachment(s)

1. ☐ Notice of References Cited (PTO-892)
2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-948)
3. ☐ Information Disclosure Statements (PTO-1449 or PTO/SB/08), Paper No./Mail Date _____
4. ☐ Examiner's Comment Regarding Requirement for Deposit of Biological Material
5. ☐ Notice of Informal Patent Application (PTO-152)
6. ☐ Interview Summary (PTO-413), Paper No./Mail Date _____ .
7. ☐ Examiner's Amendment/Comment
8. ☒ Examiner's Statement of Reasons for Allowance
9. ☐ Other _____.

/[illegible]AIR ZARABIAN/
[illegible] PATENT EXAMINER
[illegible]LOGY CENTER 2800

DETAILED ACTION

This office action is in response to the filing of the after final amendment on 2 December 2004. Claims 7-18 are pending; claims 1-6 have been cancelled.

Allowable Subject Matter

Claims 7-18 are allowed.

Reasons for Allowance

The following is an examiner's statement of reasons for allowance: prior art does not anticipate, teach, or suggest a method of manufacturing a semiconductor device where a semiconductor layer is formed on a substrate; selectively ion-implanting an expansion element in a first region of the substrate; selectively ion-implanting a compression element in a second region of the substrate; annealing to expand the first region and to compress the second region, wherein the expanded first region pushes up a first portion of the semiconductor layer and the compressed second region pulls down a second portion of the semiconductor layer; and forming an N type device on the first portion of the semiconductor layer; and forming a P type device on the second portion of the semiconductor layer.

For example, Doyle et al. (6,228,694) disclose a method for manufacturing a semiconductor device where a semiconductor layer is formed on a substrate; forming an oxide layer between the semiconductor layer and the substrate; expanding a first region of the substrate to push up a first portion of the semiconductor layer;

compressing a second region of the substrate to pull down a second portion of the semiconductor layer; forming an N type device over the first portion of the semiconductor layer; and forming a P type device over the second portion of the semiconductor layer.

However, Doyle et al. do not disclose, anticipate, teach, or suggest selectively ion-implanting an expansion element in a first region of the substrate; selectively ion-implanting a compression element in a second region of the substrate; annealing to expand the first region and to compress the second region, wherein the expanded first region pushes up a first portion of the semiconductor layer and the compressed second region pulls down a second portion of the semiconductor layer.

The prior art made of record in this action does not anticipate, teach, or suggest a method of manufacturing a semiconductor device where a semiconductor layer is formed on a substrate; selectively ion-implanting an expansion element in a first region of the substrate; selectively ion-implanting a compression element in a second region of the substrate; annealing to expand the first region and to compress the second region, wherein the expanded first region pushes up a first portion of the semiconductor layer and the compressed second region pulls down a second portion of the semiconductor layer; and forming an N type device on the first portion of the semiconductor layer; and forming a P type device on the second portion of the semiconductor layer.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably

accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Pamela E Perkins whose telephone number is (571) 272-1840. The examiner can normally be reached on Monday thru Friday, 9:00am to 5:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on (571) 272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

PEP

AMIR ZARABIAN
PRIMARY PATENT EXAMINER
TECHNOLOGY CENTER 2800